

## 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

#### Notification#20231207005.0 Device symbolization update for Select Devices Information Only

Date: December 08, 2023 To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team SC Business Services

#### 20231207005.0 Attachment: 1

### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	<b>CUSTOMER PART NUMBER</b>
ADS1234IPWG4	null
DRV8818PWP	null
DRV8825PWP	null
MAX3222ECPWR	null
MSP430F1122IPW	null
MSP430F2012TPW	null
MSP430F2132IPW	null
MSP430G2452IPW20R	null
MSP430G2553IPW20R	null
MSP430G2553IPW28R	null
PCM5102AQPWRQ1	null
SN74LVC244APW	null
THS7374IPW	null
TLC 59116IPWR	null
TLC 5940PWP	null
TPA3124D2PWPR	null
TPS767D301PWP	null
TPS767D301QPWPRQ1	null
TXB0108PWR	null
UCC28950PW	null

Technical details of this Product Change follow on the next page(s).

Notification Number: 20231		231207005.0		Notification Date:			December 08, 2023			
Title: Device symbolization update for Select Devices										
Customer Contact: Change Management team				Dept:	Quality Services					
Change Type:										
Assembly Site		Design				Wafer Bu	mp Material			
🗌 As	sembly Process			Data Sheet				Wafer Bu	mp Process	
Assembly Materials Dart number change		e		Wafer Fal	b Site					
Me Me	echanical Specif	icatio	n	Test Site				Wafer Fa	b Materials	
🛛 Pa	cking/Shipping/	'Labe	ling		Test Process				Wafer Fa	b Process

# **Notification Details**

#### **Description of Change:**

Texas Instruments Incorporated is announcing an update to device symbolization marking for Select Devices as follows:

**Change #1**: All devices will start having the mold cavity id included in the device marking for enhanced device level traceability as follows:

	Current	New
Visual	SN509066 DK231480 P55LL1LT \$2 A0G4	SN509066 DK231480 P65LLLLT AOGA XXXXX - Unit ID coordinate
Pin 1 mark	Embossed	Dot

**Change #2:** Devices Symbolization update (for this change below, some of the devices were on previous PCNs for this change):

	Current	New
**ECAT	Include Value	Remove
TI Bug	Include	Replace with "TI" text

	Image: A constraint of the symbolization, but for the symbolization will be removed.					
Reason for Change:						
Improved internal traceability						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):						
Device marking change only						
Changes to product identification resulting from this notification:						
Device marking change only. No change to pack labels.						
Product Affected:						
See page 2						

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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